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L14 ANSWER 1 OF 3 JAPIO COPYRIGHT 1996 JPO and JapioFAMILY 1  
AN 90-284438 JAPIO  
TI METHOD OF MOUNTING SEMICONDUCTOR DEVICE  
IN HASHIMOTO NOBUAKI  
PA SEIKO EPSON CORP, JP (CO 000236)  
PI JP 02284438 A 19901121 Heisei  
AI JP 89-106427 (JP01106427 Heisei) 19890426  
SO PATENT ABSTRACTS OF JAPAN, Unexamined Applications, Section: E,  
Sect. No. 1032, Vol. 15, No. 58, P. 6 (19910212)  
IC ICM (5) H01L021-603

L14 ANSWER 2 OF 3 INPADOC COPYRIGHT 1996 EPO FAMILY 1  
AN 17952831 INPADOC EW 9125 UP 910629  
TI METHOD OF MOUNTING SEMICONDUCTOR DEVICE.  
IN HASHIMOTO NOBUAKI  
INS HASHIMOTO NOBUAKI  
PA SEIKO EPSON CORP  
PAS SEIKO EPSON CORP  
DT Patent  
PIT JPA2 DOCUMENT LAID OPEN TO PUBLIC INSPECTION  
PI JP 02284438 A2 901121  
AI JP 89-106427 A 890426  
PRAI JP 89-106427 A 890426  
OSDW 91-011291  
OSJP 150058E0000006

L14 ANSWER 3 OF 3 WPIDS COPYRIGHT 1996 DERWENT INFORMATION LTD  
FAMILY 1  
AN 91-011291 [02] WPIDS  
TI Mounting semiconductor device to reduce mounting defect - includes  
conducting positioning, preliminary heating, and proper clamping of  
semiconductor device NoAbstract Dwg 1/3.  
DC U11 U14  
PA (SHIH) SEIKO EPSON CORP  
CYC 1  
PI JP 02284438 A 901121 (9102)\*  
ADT JP 02284438 A JP 89-106427 890426  
PRAI JP 89-106427 890426  
IC H01L021-60

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